

REVISIONS																								
LTR	DESCRIPTION										DATE (YR-MO-DA)				APPROVED									
F	Change to military drawing format. Changes in table I tests. Add case outline 2 to drawing. Editorial changes throughout.										87-06-09				N. A. Hauck									
G	Drawing updated to reflect current requirements. Editorial changes throughout. – drw										00-11-07				Raymond Monnin									
The original first page of this drawing has been replaced. Current CAGE code 67268																								
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PMIC N/A					PREPARED BY					DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43216														
					Marcia B. Kelleher																			
STANDARD MICROCIRCUIT DRAWING THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE AMSC N/A					CHECKED BY					MICROCIRCUITS, LINEAR, DUAL, DIFFERENTIAL LINE RECEIVER, MONOLITHIC SILICON														
																				Da DiCenzo				
					APPROVED BY															N. A. Hauck				
										DRAWING APPROVAL DATE														
					79-04-09																			
					REVISION LEVEL					SIZE		CAGE CODE		79008										
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										1 OF 9														

1. SCOPE

1.1 Scope. This drawing describes device requirements for MIL-STD-883 compliant, non-JAN class level B microcircuits in accordance with MIL-PRF-38535, appendix A.

1.2 Part or Identifying Number (PIN). The complete PIN is as shown in the following example:

<u>79008</u>	<u>01</u>	<u>C</u>	<u>A</u>
Drawing number	Device type (see 1.2.1)	Case outline (see 1.2.2)	Lead finish (see 1.2.3)

1.2.1 Device type. The device type identify the circuit function as follows:

<u>Device type</u>	<u>Generic number</u>	<u>Circuit function</u>
01	55182, 7820A	Dual, differential line receiver

1.2.2 Case outlines. The case outlines are as designated in MIL-STD-1835 and as follows:

<u>Outline letter</u>	<u>Descriptive designator</u>	<u>Terminals</u>	<u>Package style</u>
C	GDIP1-T14 or CDIP2-T14	14	Dual-in-line
D	GDFP1-F14 or CDFP2-F14	14	Flat pack
2	CQCC1-N20	20	Square leadless chip carrier

1.2.3 Lead finish. The lead finish is as specified in MIL-PRF-38535, appendix A.

1.3 Absolute maximum ratings.

Supply voltage V_{CC} <u>1/</u>	8 V dc
Common mode input voltage.....	± 20 V dc
Differential input voltage <u>2/</u>	± 20 V dc
Strobe input voltage.....	8 V dc
Output sink current	50 mA
Power dissipation, P_D ($T_A \leq 70^\circ\text{C}$)	600 mW <u>3/</u>
Storage temperature range.....	-65°C to $+150^\circ\text{C}$
Lead temperature (soldering 10 seconds).....	300°C
Thermal resistance, junction to case (θ_{JC}):	See MIL-STD-1835
Junction temperature (T_J)	150°C

1/ All voltage values, except differential voltages, are with respect to the network terminal.

2/ Differential voltage values are at the noninverting terminal with respect to the inverting terminal.

3/ Derate linearly 10 mW/ $^\circ\text{C}$ over 95°C ambient for C package and 8.3 mW/ $^\circ\text{C}$ over 75°C ambient for the D package.

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1.4 Recommended operating conditions.

Supply voltage 4.5 V dc to 5.5 V dc
Common mode input voltage..... ± 15 V dc
High level output current, I_{OH} -400 μ A
Low level output current, I_{OL} 16 mA
Ambient operating temperature range (T_A) -55°C to +125°C

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DoDISS) and supplement thereto, cited in the solicitation.

SPECIFICATION

DEPARTMENT OF DEFENSE

MIL-PRF-38535 - Integrated Circuits, Manufacturing, General Specification for.

STANDARDS

DEPARTMENT OF DEFENSE

MIL-STD-883 - Test Method Standard Microcircuits.
MIL-STD-973 - Configuration Management.
MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

HANDBOOKS

DEPARTMENT OF DEFENSE

MIL-HDBK-103 - List of Standard Microcircuit Drawings (SMD's).
MIL-HDBK-780 - Standard Microcircuit Drawings.

(Unless otherwise indicated, copies of the specification, standards, and handbooks are available from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

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3. REQUIREMENTS

3.1 Item requirements. The individual item requirements shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein. Product built to this drawing that is produced by a Qualified Manufacturer Listing (QML) certified and qualified manufacturer or a manufacturer who has been granted transitional certification to MIL-PRF-38535 may be processed as QML product in accordance with the manufacturers approved program plan and qualifying activity approval in accordance with MIL-PRF-38535. This QML flow as documented in the Quality Management (QM) plan may make modifications to the requirements herein. These modifications shall not affect form, fit, or function of the device. These modifications shall not affect the PIN as described herein. A "Q" or "QML" certification mark in accordance with MIL-PRF-38535 is required to identify when the QML flow option is used.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535, appendix A and herein.

3.2.1 Case outlines. The case outlines shall be in accordance with 1.2.2 herein.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 1.

3.3 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full ambient operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.

3.5 Marking. Marking shall be in accordance with MIL-PRF-38535, appendix A. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked as listed in MIL-HDBK-103 (see 6.6 herein). For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device.

3.6 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-PRF-38535, appendix A and the requirements herein.

3.7 Certificate of conformance. A certificate of conformance as required in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.

3.8 Notification of change. Notification of change to DSCC-VA shall be required in accordance with MIL-PRF-38535, appendix A.

3.9 Verification and review. DSCC, DSCC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

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TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions <u>1/</u> -55°C ≤ T _A ≤ +125°C V _{STROBE} ≥ 2.1 V unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
High level output voltage	V _{OH}	I _{OH} = -400 μA	1, 2, 3	All	2.5	5.5	V
Low level output voltage	V _{OL}	I _{OH} = 16 mA	1, 2, 3	All		0.4	V
Differential input high threshold voltage	V _{TH}	V _{CM} = 0 V	1, 2, 3	All		0.5	V
		V _{CM} = -15 V to +15 V				1	
Differential input low threshold voltage	V _{TL}	V _{CM} = 0 V	1, 2, 3	All		-0.5	V
		V _{CM} = -15 V to +15 V				-1	
High level strobe current	I _{SH}	V _{STROBE} = 5.5 V	1, 2, 3	All		5	μA
Low level strobe current	I _{SL}	V _{STROBE} = 0 V	1, 2, 3	All		-1.4	mA
Inverting input current	I _{IN} ⁻	V _{CM} = 15 V, V _{ID} = 1 V	1, 2, 3	All		4.2	mA
		V _{CM} = 0 V, V _{ID} = -0.5 V				0.5	
		V _{CM} = -15 V, V _{ID} = -1 V				-4.2	
Noninverting input current	I _{IN} ⁺	V _{CM} = 15 V	1, 2, 3	All		7	mA
		V _{CM} = 0 V				-1.6	
		V _{CM} = -15 V				-9.8	
Supply current (each receiver)	I _{CC}	V _{CM} = 15 V, V _{ID} = 1 V	1, 2, 3	All		7	mA
		V _{CM} = 0 V, V _{ID} = -0.5 V				10.2	
		V _{CM} = -15 V, V _{ID} = -1 V				15	

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TABLE I. Electrical performance characteristics - continued.

Test	Symbol	Conditions <u>1</u> / -55°C ≤ T _A ≤ +125°C V _{STROBE} ≥ 2.1 V unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Inverting input resistance	R _I		1, 2, 3	All	3.6		kΩ
Noninverting input resistance	R _{NI}		1, 2, 3	All	1.8		kΩ
Line terminating resistance	R _T		1, 4	All	120	250	Ω
Propagation delay time low to high output from differential input	t _{PLHD}	R _L = 400 Ω, C _L = 15 pF	9	All		40	ns
			10, 11			60	
Propagation delay time high to low output from differential input	t _{PHLD}	R _L = 400 Ω, C _L = 15 pF	9	All		45	ns
			10, 11			75	
Propagation delay time low to high level output from strobe input	t _{PLHS}	R _L = 400 Ω, C _L = 15 pF	9	All		30	ns
			10, 11			50	
Propagation delay time high to low level output from strobe input	t _{PHLS}	R _L = 400 Ω, C _L = 15 pF	9	All		25	ns
			10, 11			45	

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Device type	All	
Case outline	C and D	2
Terminal number	Terminal symbol	
1	1IN-	NC
2	1R _T	1IN-
3	1IN+	1R _T
4	1STRB	1IN+
5	1RTC	NC
6	1OUT	1STRB
7	GND	NC
8	2OUT	1RTC
9	2RTC	1OUT
10	2STRB	GND
11	2IN+	NC
12	2R _T	2OUT
13	2IN-	2RTC
14	V _{CC}	2STRB
15	---	NC
16	---	2IN+
17	---	NC
18	---	2R _T
19	---	2IN-
20	---	V _{CC}

FIGURE 1. Terminal connections.

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4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.

4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:

- a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
 - (2) $T_A = +125^{\circ}\text{C}$, minimum.
- b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)
Interim electrical parameters (method 5004)	1
Final electrical test parameters (method 5004)	1*, 2, 3, 9
Group A test requirements (method 5005)	1, 2, 3, 4, 9, (10, 11)**
Groups C and D end-point electrical parameters (method 5005)	1, 2, 3

* PDA applies to subgroup 1.

** Subgroups 10 and 11, if not tested, shall be guaranteed to the specified limits in table I.

4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

4.3.1 Group A inspection.

- a. Tests shall be as specified in table II herein.
- b. Subgroups 5, 6, 7, and 8 in table I, method 5005 of MIL-STD-883 shall be omitted.

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4.3.2 Groups C and D inspections.

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test conditions, method 1005 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
 - (2) $T_A = +125^{\circ}\text{C}$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38535, appendix A.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.3 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.

6.4 Record of users. Military and industrial users shall inform Defense Supply Center Columbus when a system application requires configuration control and the applicable SMD. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0525.

6.5 Comments. Comments on this drawing should be directed to DSCC-VA, Columbus, Ohio 43216-5000, or telephone (614) 692-0674.

6.6 Approved sources of supply. Approved sources of supply are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DSCC-VA.

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STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 00-11-07

Approved sources of supply for SMD 79008 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535.

Standard microcircuit drawing PIN <u>1</u> /	Vendor CAGE number	Vendor similar PIN <u>2</u> /
79008012A	01295	SNJ55182FK
7900801CA	01295	SNJ55182J
7900801DA	01295	SNJ55182W

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- 2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE
number

01295

Vendor name
and address

Texas Instruments, Inc.
Semiconductor Group
8505 Forest Ln.
PO Box 660199
Dallas, TX 75243
Point of contact:

U.S. Highway 75 South
P.O. Box 84, M/S 853
Sherman, TX 75090-9493

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